AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

- 1. (original): A conductive composition comprising a particulate silver compound and a binder.
- 2. (original): A conductive composition comprising a particulate silver compound, a reducing agent and a binder.
- 3. (currently amended): <u>The</u>A conductive composition according to either one of claim 1 and or claim 2, wherein said particulate silver compound is one or more of silver oxide, silver carbonate and silver acetate.
- 4. (currently amended): <u>TheA</u> conductive composition according to <u>any one of either</u> claim 1 <u>throughor</u> claim 32, wherein an average particle diameter of said particulate silver compound is within a range from 0.01 to 10 μm.
- 5. (currently amended): TheA conductive composition according to any one of either claim 1 throughor claim [4]2, wherein said binder is one or more materials selected from a group consisting of polyvalent phenol compounds, phenol resins, alkyd resins, polyester resins and epoxy resins.
- 6. (currently amended): <u>The</u>A conductive composition according to <u>any one of either</u> claim 1 throughor claim 52, wherein said binder exhibits a reducing action.

PRELIMINARY AMENDMENT

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- 7. (currently amended): <u>The</u>A conductive composition according to <u>any one of either</u> claim 1 throughor claim 42, wherein said binder is a fine powder of a thermoplastic resin with an average particle diameter within a range from 20 nm to 5 μm.
- 8. (currently amended): <u>The</u>A conductive composition according to claim 7, wherein said thermoplastic resin is polystyrene or polyethylene terephthalate.
- 9. (currently amended): TheA conductive composition according to any one of claim 2 through claim 8, wherein said reducing agent is one or more of ethylene glycol, diethylene glycol, triethylene glycol and ethylene glycol diacetate.
- 10. (currently amended): <u>The</u>A conductive composition according to <u>any one of either</u> claim 1 throughor claim 92, having a viscosity within a range from 30 to 300 dPa·sec.
- 11. (currently amended): A method of forming a conductive coating comprising the steps of applying and then heating a conductive composition according to any one of either claim throughor claim 102.
- 12. (currently amended): <u>The</u>A method of forming a conductive coating according to claim 11 wherein a heating temperature is within a range from 140 to 200°C.
- 13. (currently amended): A conductive coating, produced by a formation method according to either one of claim 11 and claim-12, wherein silver particles are fused together.
- 14. (currently amended): TheA conductive coating according to claim 13, having a volume resistivity of no more than $3.0 \times 10^{-5} \Omega$ cm or less.